



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



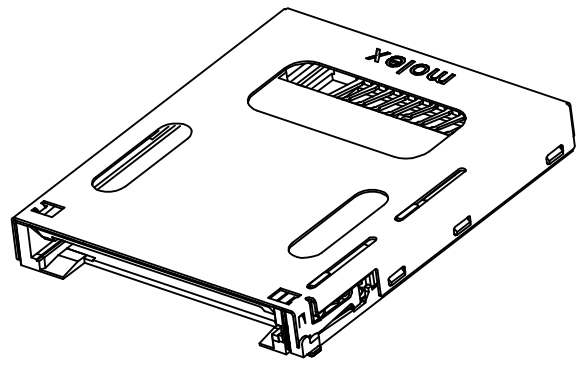
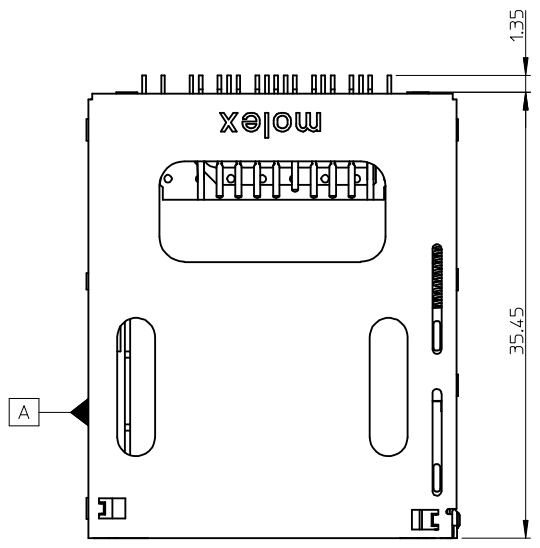
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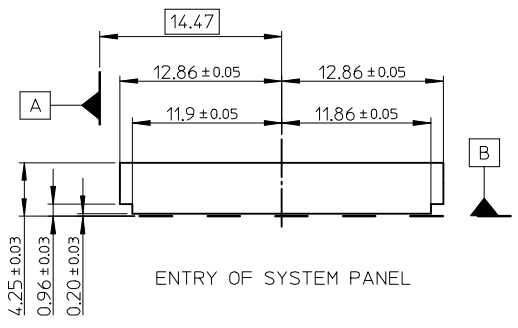
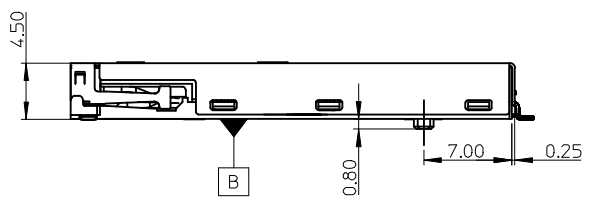
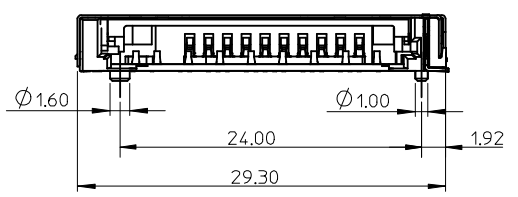


NOTE:

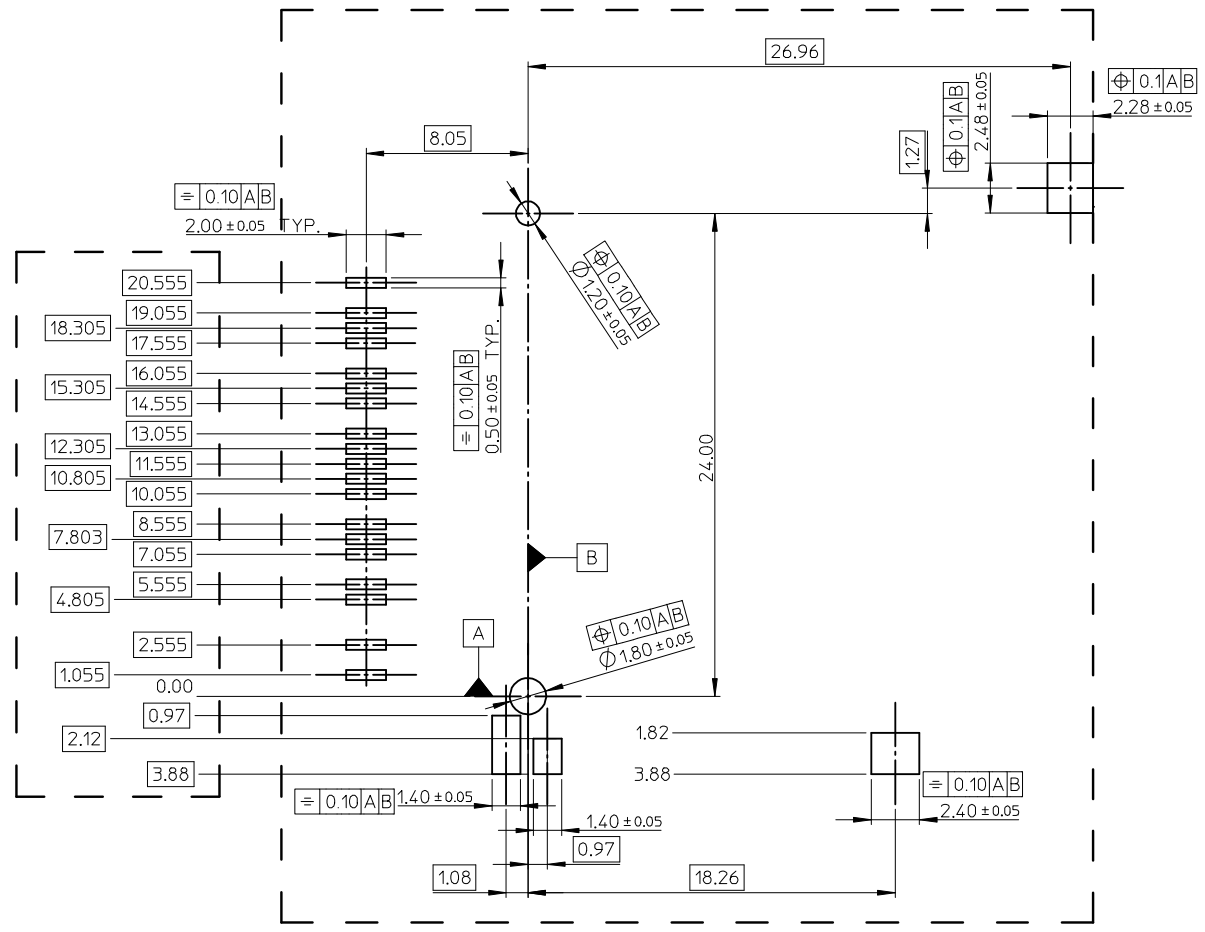
1.MATERIALS:
 HOUSING: HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94 V-0.
 TERMINAL : NAIL AND SWITCH: COPPER ALLOY.
 METAL SHELL: STAINLESS STEEL

2.FINISH:
 TERMINAL: NICKEL OVERALL UNDERPLATING, THICKNESS : 1.27 MICROMETER MIN. SELECTIVE GOLD ON CONTACT AREA, THICKNESS : 0.2 MICROMETER MIN. TIN ALLOY ON SOLDER AREA. THICKNESS : 3 MICROMETER MIN.
 SWITCH: NICKEL OVERALL UNDERPLATING, THICKNESS : 1.27 MICROMETER MIN. SELECTIVE GOLD ON CONTACT AREA, THICKNESS : 0.05 MICROMETER MIN. TIN ALLOY ON SOLDER AREA. THICKNESS : 3 MICROMETER MIN.
 NAIL: NICKEL OVERALL UNDERPLATING, THICKNESS : 1.27 MICROMETER MIN. TIN ALLOY ,THICKNESS : 3 MICROMETER MIN. ON SOLDER AREA

3.COPLANARITY: 0.15 MAX.
 4.PRODUCT SPECIFICATION: PS-48000-001
 5.PACKAGING: PK-48000-001
 6.PRODUCT COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV 2000/53/EC.



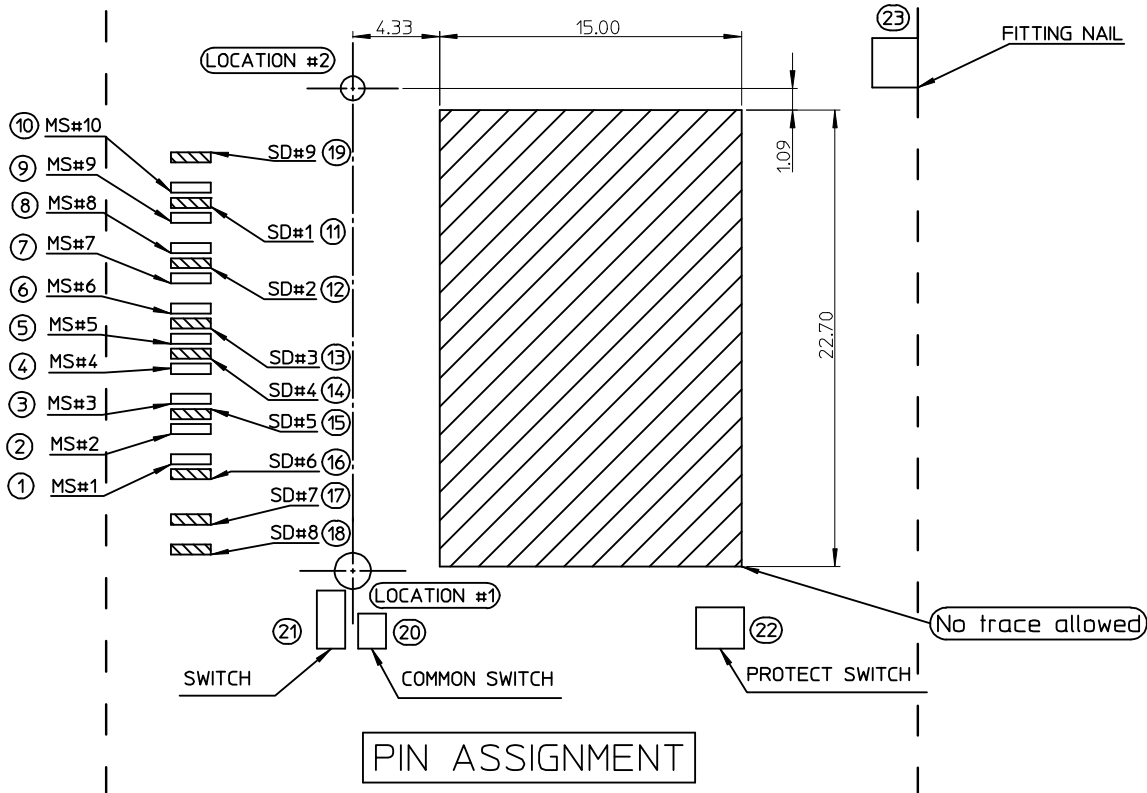
UPDATE DRAWING	EC NO:	2008/08/14	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	DRWNL:SONG09			mm	INCH	MM ONLY	1:1	METRIC		
D	CHKD:		DESCRIPTION	4 PLACES	± ---	± ---	DRAWN BY	DATE	TITLE	
	APPR:			3 PLACES	± ---	± ---	FOX.WU	2003/09/04		
				2 PLACES	± 0.25	± ---	CHECKED BY	DATE	3 IN 1 MEMORY COMBO CONNECTOR PUSH PUSH TYPE	
				1 PLACE	± 0.25	± ---	W.CHANG	2003/09/05		
				ANGULAR ± 3 °			APPROVED BY	DATE	MOLEX INCORPORATED	
				DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			E.LAN	2003/09/05		
							MATERIAL NO.	DOCUMENT NO.	SHEET NO.	
							480002001	SD-48000-201	1 OF 5	
							THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



FOOT PRINT

RECOMMENDED PCB THICKNESS : 1.0 mm

UPDATE DRAWING EC NO: SH2009-0083 DRW: NLSONG09 2008/08/14 CHKD: APPR:	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 1:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION			
		4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	2 PLACES ± 0.25 ± ---	1 PLACE ± 0.25 ± ---	mm INCH	DRAWN BY FOX.WU	DATE 2003/09/04	TITLE 3 IN 1 MEMORY COMBO CONNECTOR PUSH PUSH TYPE		
		ANGULAR ± 3 °				DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	CHECKED BY W. CHANG	DATE 2003/09/05			
		MATERIAL NO. 480002001		DOCUMENT NO. SD-48000-201		SHEET NO. 2 OF 5					



SD CARD CIRCUIT	

WITHOUT CARD	
#21 SW 0--	--0 #20 GND
#22 WP 0--	--0 #20 GND

CARD INSERTED	
WRITE PROTECT LOCK	
#21 SW 0-----0	#20 GND
#22 WP 0--	--0 #20 GND

CARD INSERTED	
WRITE PROTECT UNLOCK	
#21 SW 0-----0	#20 GND
#22 WP 0-----0	#20 GND

THE SD CARD CONTACTS ARE CONTACTED IN THREE STEPS :

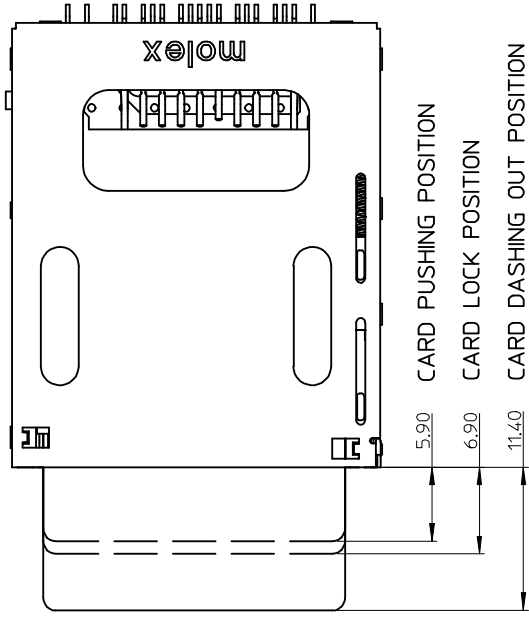
1. GROUND VSS (PIN3) AND SUPPLY VOLTAGE VDD (PIN4).
2. CLK,CMD,DAT0,DAT1,DAT2 AND VSS (PIN6)
3. CD/DAT3 (PIN1)

1	MS-1P (Vss)	15	SD-5P (CLK)
2	MS-2P (BS)	16	SD-6P (Vss)
3	MS-3P (DATA1)	17	SD-7P (DAT0)
4	MS-4P (SDIO/DATA0)	18	SD-8P (DAT1)
5	MS-5P (DATA2)	19	SD-9P (DAT2)
6	MS-6P (INS)	20	SD-SW (GND)
7	MS-7P (DATA3)	21	SW (RSV)
8	MS-8P (SCLK)	22	SD-SW (WP)
9	MS-9P (Vcc)	23	FITTING NAIL
10	MS-10P (Vss)		
11	SD-1P (CD/DAT3)		
12	SD-2P (CMD)		
13	SD-3P (Vss)		
14	SD-4P (Vdd)		

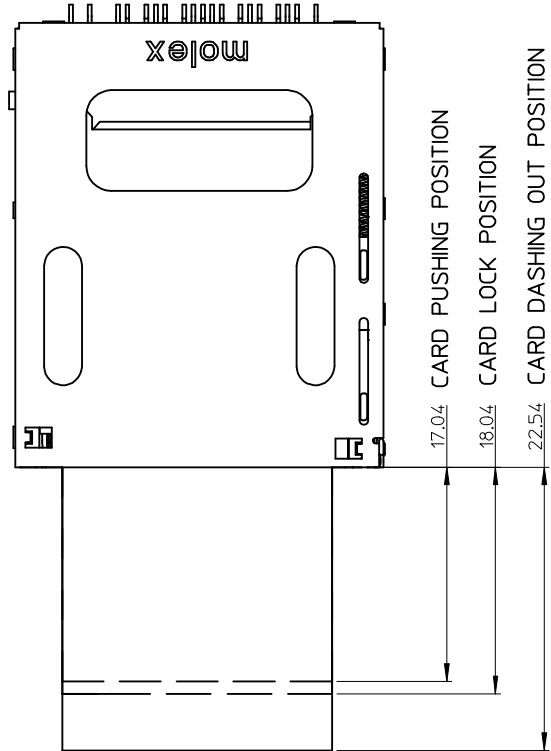
PIN ASSIGNMENT

UPDATE DRAWING EC NO: DRWINL.SONG09 CH'KD: 2008/08/14 APPR:	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▼=0 ▽=0	mm INCH	MM ONLY	1:1	METRIC	
		4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.25 ± --- 1 PLACE ± 0.25 ± --- ANGULAR ± 3 °	DRAWN BY DATE FOX.WU 2003/09/04 CHECKED BY DATE W.CHANG 2003/09/05 APPROVED BY DATE E.LAN 2003/09/05	TITLE	3 IN 1 MEMORY COMBO CONNECTOR PUSH PUSH TYPE	
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. DOCUMENT NO. SHEET NO.	MOLEX INCORPORATED		3 OF 5
			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

10 9 8 7 6 5 4 3 2 1



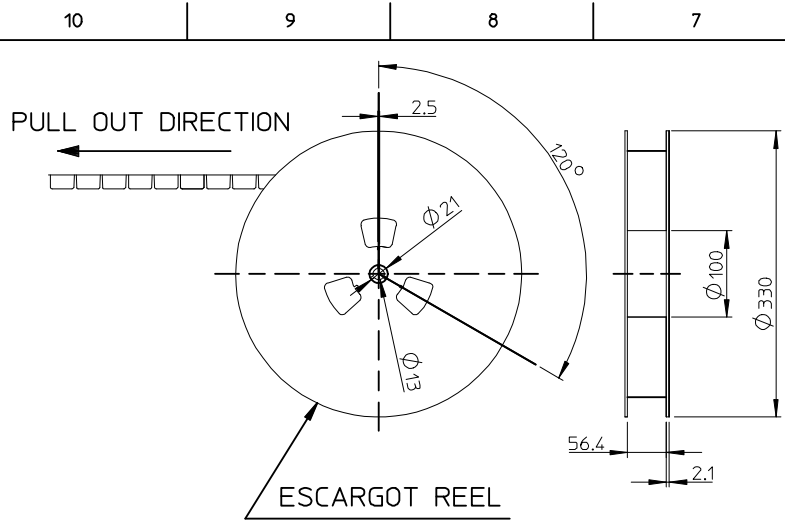
MMC/SD card



MS card

UPDATE DRAWING EC NO: SHZ009-0083 DRWN: LSONG09 2008/08/14 CHKD: APPR:	DESCRIPTION REV	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED) 4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.25 ± --- 1 PLACE ± 0.25 ± --- ANGULAR ± 3 °	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
		▼=0 □=0		MM ONLY	1:1	METRIC	
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		DRAWN BY: FOX.WU CHECKED BY: W.CHANG APPROVED BY: E.LAN MATERIAL NO. 480002001	DATE: 2003/09/04 DATE: 2003/09/05 DATE: 2003/09/05	TITLE: 3 IN 1 MEMORY COMBO CONNECTOR PUSH PUSH TYPE	
		SIZE A3 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		MOLEX INCORPORATED DOCUMENT NO. SD-48000-201	SHEET NO. 4 OF 5		

9 8 7 6 5 4 3 2 1

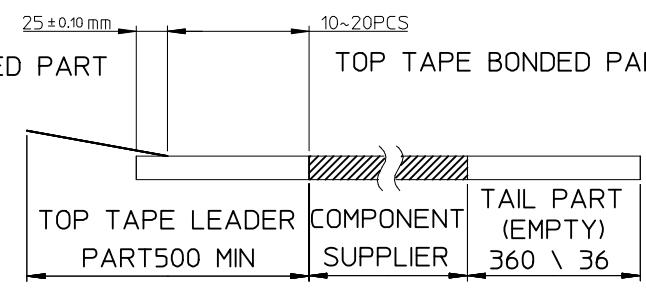


NOTES

1. NUMBER OF CONNECTORS: 250 PCS/REEL

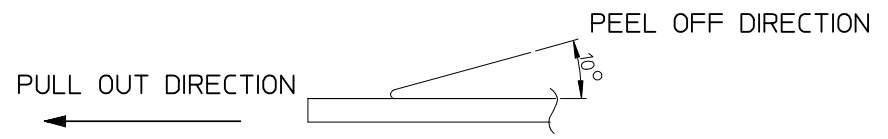
TOP TAPE NON-BONDED PART

TOP TAPE BONDED PART (EMPTY)

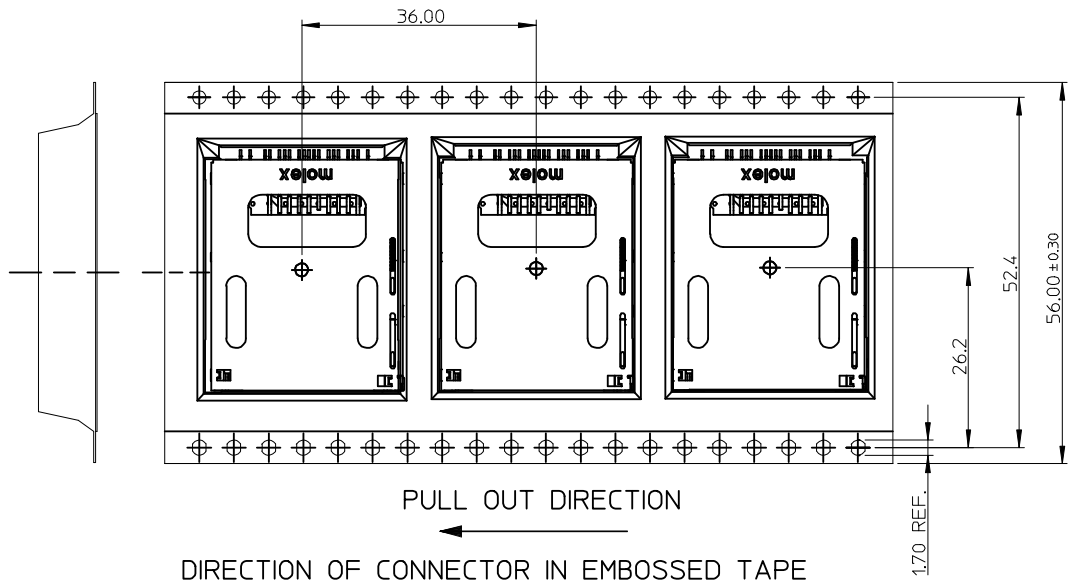


PULL OUT DIRECTION

3. PEEL OFF FORCE OF TOP TAPE: 0.1~1.3 N (10.2~130gf)
 PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
 (PEEL OFF SPEED: 300mm/min.REF.)



4. PACKAGING DRAWING REFERS TO PK-48000-001



PULL OUT DIRECTION
 DIRECTION OF CONNECTOR IN EMBOSSED TAPE

UPDATE DRAWING	2008/08/14
EC NO: SH2009-0083	
DRWN: L.SONG	
CHKD: X.J.SONG	
APPR: H.WANG	
REV	DESCRIPTION

QUALITY SYMBOLS	▽=0
	∇=0

GENERAL TOLERANCES (UNLESS SPECIFIED)	mm	INCH	
	4 PLACES	± ---	± ---
	3 PLACES	± ---	± ---
	2 PLACES	± 0.25	± ---
	1 PLACE	± 0.25	± ---
ANGULAR ± 3 °			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			

DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
MM ONLY		1:1	METRIC	
DRAWN BY	DATE	TITLE		
FOX.WU	2003/09/04	3 IN 1 MEMORY COMBO CONNECTOR PUSH PUSH TYPE		
CHECKED BY	DATE			
W.CHANG	2003/09/05			
APPROVED BY	DATE	MOLEX INCORPORATED		
E.LAN	2003/09/05			
MATERIAL NO.	DOCUMENT NO.	SHEET NO.		
480002001	SD-48000-201	5 OF 5		